ABSTRACT OF THE DISCLOSURE

A resin substrate is made of resin or a composite material containing resin. Pins each having the surface, on which Au plating is formed, are, with a soldering material made of Sn and Sb, soldered to a substrate body having a first main surface and formed into substantially a rectangular shape to project over the first main surface 2A of the substrate body. Wettability of the soldering material for securing the pins and the substrate body to one another is relatively low as compared with that of a Pb-Sn soldering material. Therefore, the height of upward movement of the soldering material along the pin can be reduced. Hence it follows that the pins can sufficiently deeply be inserted into the socket so that the gap between the first main surface of the substrate body and the upper surface of the socket is reduced. As a result, the overall height realized after the substrate made of resin has been joined to the socket can be reduced

This Sheet Has Been Replaced

